

FQE10N20C

200V N-Channel MOSFET

General Description

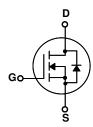
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supplies and motor controls.

Features

- 4.0A, 200V, R_DS(on) = 0.36 Ω @V_GS = 10 V Low gate charge (typical 20 nC)
- Low Crss (typical 40.5 pF)
- Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	FQE10N20C	Units	
V _{DSS}	Drain-Source Voltage		200	V
I _D	Drain Current - Continuous (T _C = 25	°C)	4.0	Α
	- Continuous (T _C = 10	0°C)	2.5	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	16	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	320	mJ
I _{AR}	Avalanche Current	(Note 1)	4.0	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	1.28	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P _D	Power Dissipation (T _C = 25°C)		12.8	W
	- Derate above 25°C		0.10	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering 1/8" from case for 5 seconds	flaximum lead temperature for soldering purposes, /8" from case for 5 seconds		

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		9.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced t	o 25°C		0.28		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V				10	μА
		V _{DS} = 160 V, T _C = 125°C				100	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	aracteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 2.0 A			0.29	0.36	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 2.0 A	(Note 4)		4.5		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			395 97	510 125	pF pF
C _{rss}	Reverse Transfer Capacitance			40.5	53	pF	
Switchi	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 9.5 A,			11	30	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$			92	190	ns
t _{d(off)}	Turn-Off Delay Time				70	150	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		72	160	ns
Qg	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_{D} = 9.5 \text{ A},$			20	26	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V			3.1		nC
Q_{gd}	Gate-Drain Charge	((Note 4, 5)		10.5		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings	1				
Is	Maximum Continuous Drain-Source Dic					4.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F					16	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 4.0 \text{ A}$				1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 9.5 \text{ A},$			158		ns
Q_{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)			0.97		μC

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = $30\,\text{mH}$, I $_{AS} = 4.0$ A, V $_{DD} = 50$ V, R $_{G} = 25$ Ω , Starting T $_{J} = 25$ °C 3. I $_{SD} \le 9.5$ A, di/dt ≤ 300 A $_{HS}$, V $_{DD} \le BV_{DS}$, Starting T $_{J} = 25$ °C 4. Pulse Test : Pulse width ≤ 300 \mus, Duty cycle $\le 2\%$ 5. Essentially independent of operating temperature

Typical Characteristics

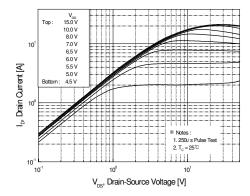


Figure 1. On-Region Characteristics

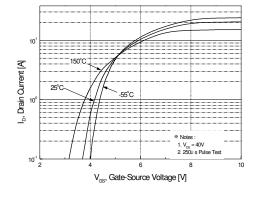


Figure 2. Transfer Characteristics

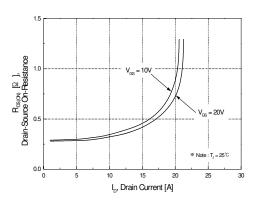


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

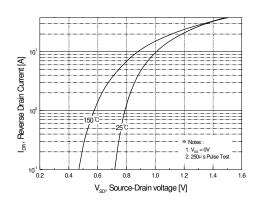


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

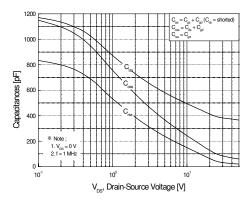


Figure 5. Capacitance Characteristics

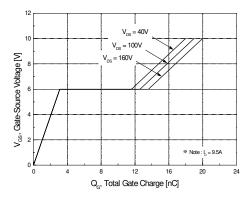


Figure 6. Gate Charge Characteristics

©2004 Fairchild Semiconductor Corporation Rev.B, January 2004

Typical Characteristics (Continued)

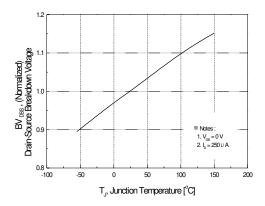
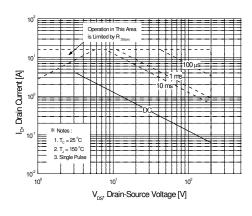


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



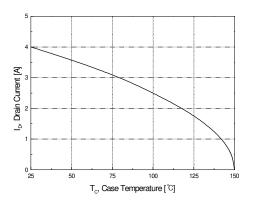


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

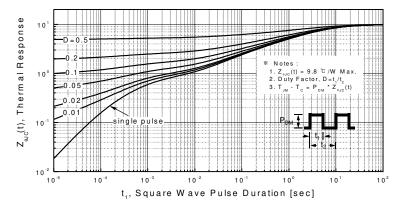
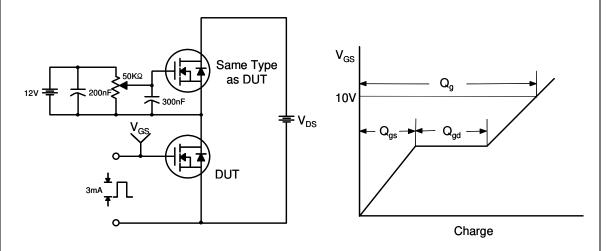


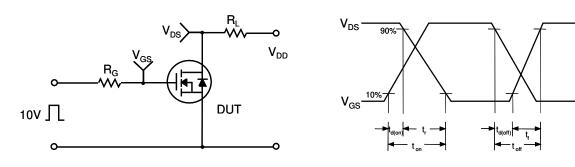
Figure 11. Transient Thermal Response Curve

©2004 Fairchild Semiconductor Corporation Rev. B, January 2004

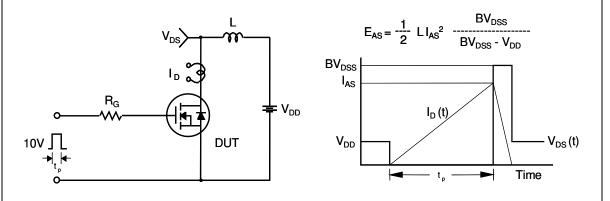
Gate Charge Test Circuit & Waveform



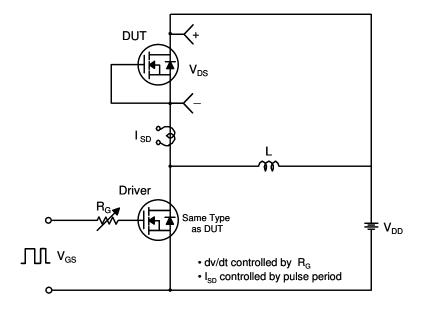
Resistive Switching Test Circuit & Waveforms

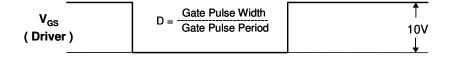


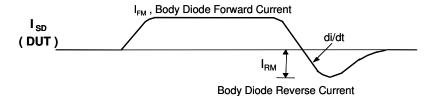
Unclamped Inductive Switching Test Circuit & Waveforms

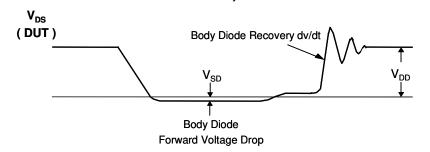


Peak Diode Recovery dv/dt Test Circuit & Waveforms



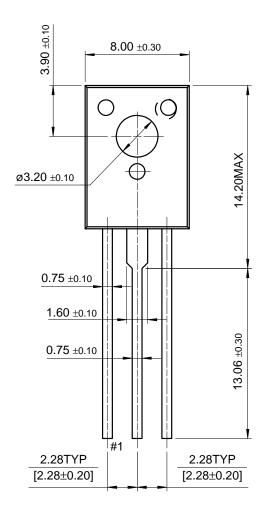


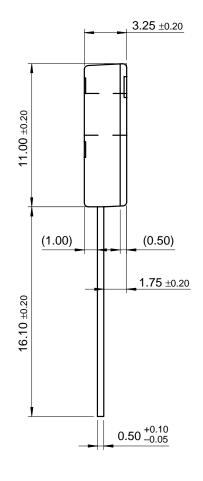




Package Dimensions

TO-126







Dimensions in Millimeters

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx [™] FACT Quiet series [™] Li	_ittleFET™	Power247™	SuperSOT™-3
ActiveArray™ FAST® M	MICROCOUPLER™	PowerTrench [®]	SuperSOT™-6
Bottomless™ FASTr™ M	MicroFET™	QFET™	SuperSOT™-8
CoolFET™ FRFET™ M	VicroPak™	QSTM	SyncFET™
CROSSVOLT™ GlobalOptoisolator™ M	MICROWIRE™	QT Optoelectronics™	TinyLogic [®]
DOME™ GTO™ M	MSX™	Quiet Series™	TINYOPTO™
EcoSPARKTM HiSeCTM M	MSXPro™	RapidConfigure™	TruTranslation™
E ² CMOS TM I ² C TM O	OCX™	RapidConnect™	UHC™
EnSigna™ ImpliedDisconnect™ O	OCXPro™	SILENT SWITCHER®	UltraFET [®]
FACT™ ISOPLANAR™ O	OPTOLOGIC [®]	SMART START™	VCX™
Across the board. Around the world.™ O	OPTOPLANAR™	SPM™	
The Power Franchise™ P	PACMAN™	Stealth™	
Programmable Active Droop™ P	POP™	SuperFET™	

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

©2004 Fairchild Semiconductor Corporation Rev. Id

Search:

Go

DATASHEETS, SAMPLES, BUY TECHNICAL INFORMATION APPLICATIONS DESIGN CENTER SUPPORT COMPANY INVESTORS MY F.

Home >> Find products >>

FQE10N20C

200V N-Channel Advance Q-FET C-Series

Contents

General description

Qualification Support

- Features
- Product status/pricing/packaging
- Order Samples

General description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supplies and motor controls.

back to top

Features

- 4.0A, 200V, $R_{DS(on)} = 0.36\Omega @ V_{GS} = 10 \text{ V}$
- Low gate charge (typical 20 nC)
- Low Crss (typical 40.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

back to top

Product status/pricing/packaging

BUY

BUY

Datasheet Download this datasheet



e-mail this datasheet

This page Print version

Related Links

Request samples

How to order products

Product Change Notices (PCNs)

Support

Sales support

Quality and reliability

Design center

Product	Product status	Pb-free Status	Pricing*	Package type	Leads	Packing method	Package Marking Convention**
FQE10N20CTU	Full Production	Full Production	\$0.496	TO-126	3	RAIL	Line 1: \$Y (Fairchild logo) & Z (Asm. Plant Code) & 4 (4-Digit Date Code) Line 2: FQE10N20C

^{*} Fairchild 1,000 piece Budgetary Pricing

** A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a Fairchild distributor to obtain samples



Indicates product with Pb-free second-level interconnect. For more information click here.

Package marking information for product FQE10N20C is available. Click here for more information .

back to top

Qualification Support

Click on a product for detailed qualification data

Product		
FQE10N20CTU		

back to top

© 2007 Fairchild Semiconductor



Products | Design Center | Support | Company News | Investors | My Fairchild | Contact Us | Site Index | Privacy Policy | Site Terms & Conditions | Standard Terms & Conditions |